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4. Application number(s) or patent number(s): If this document is being filed together with a new application, the execution date of the application is: _____ A. Patent Application No.(s) 10/078,718 B. Patent No.(s) _____ Additional numbers attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No		
5. Name and address of party to whom correspondence concerning document should be mailed: Name: Larry L. Coats Internal Address: Coats & Bennett, PLLC _____ _____ Street Address: 1400 Crescent Green, Ste. 300 _____ City: Apex State: NC Zip: 27502		6. Total number of applications and patents involved: <input checked="" type="checkbox"/> 7. Total fee (37 CFR 3.41):\$ 40.00 <input checked="" type="checkbox"/> Enclosed <input type="checkbox"/> Authorized to be charged to deposit account 8. Deposit account number: _____ _____
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ASSIGNMENT OF PATENT

In consideration of Five and 00/100 Dollars (\$5.00) and other good and valuable consideration, of which receipt is acknowledged, we, **Yong Kee Yeo, Navas O.K. Khan, and Mahadevan K. Iyer**, owners of the entire right, title and interest in and to the improvements in an **Enhanced Chip Scale Package for Wire Bond Dies**, invented by us, and described in the application for U.S. patent Serial No. 10/078,718 filed on 19 February 2002, executed on September 13, 2001, September 19, 2001, and September 21, 2001, hereby sell and assign a certain undivided percentage interest in the entire right, title, and interest in the application for United States Patent and any and all patents granted therefore, to each of the following entities where the certain undivided percentage interest appears next to each entity in the right-hand column denoted Percentage Interest:

<u>Entity</u>	<u>Percentage Interest</u>
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The undivided respective percentage interests in the entire right, title, and interest in said application and all patents granted therefore are to be held and enjoyed by each of the above entities, their successors, and assigns, as fully and entirely as the same would have been held and enjoyed by Yong Kee Yeo, Navas O.K. Khan, and Mahadevan K. Iyer had this assignment and sale not been made.

24 Mar 03


Date

13 Mar 03


Date

13 Mar 03


Date



Yong Kee Yeo



Navas O.K. Khan



Mahadevan K. Iyer